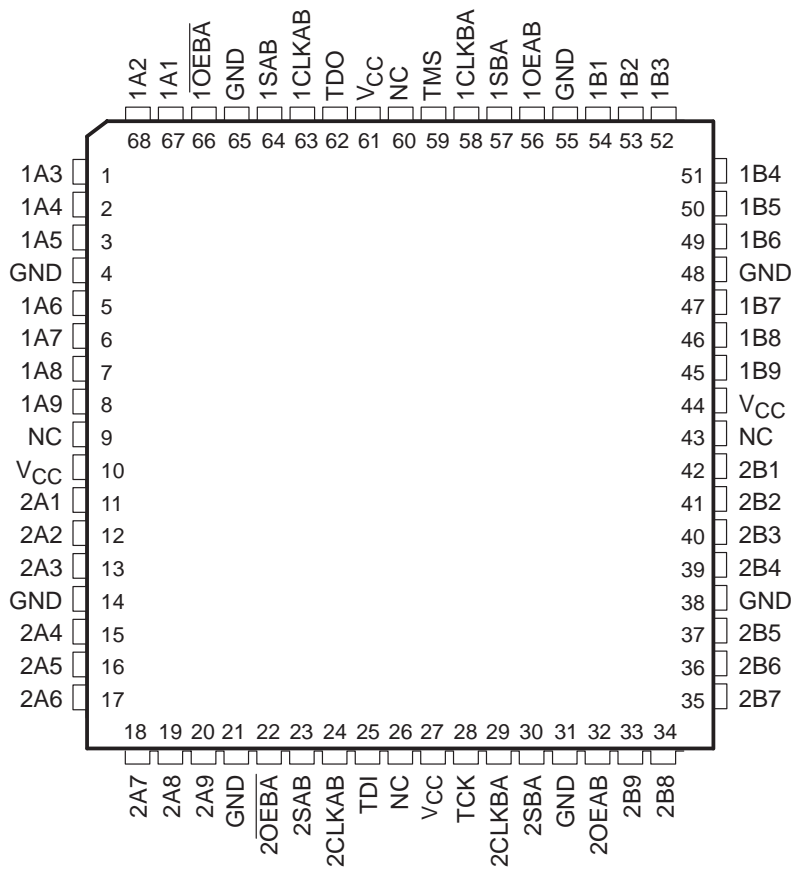


# SN54ABT18652, SN74ABT18652 SCAN TEST DEVICES WITH 18-BIT BUS TRANSCEIVERS AND REGISTERS

SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

- Members of the Texas Instruments **SCOPE™** Family of Testability Products
- Members of the Texas Instruments **Widebus™** Family
- Compatible With the IEEE Standard 1149.1-1990 (JTAG) Test Access Port and Boundary-Scan Architecture
- Include D-Type Flip-Flops and Control Circuitry to Provide Multiplexed Transmission of Stored and Real-Time Data
- Two Boundary-Scan Cells per I/O for Greater Flexibility
- State-of-the-Art **EPIC-II B™** BiCMOS Design Significantly Reduces Power Dissipation
- **SCOPE™** Instruction Set
  - IEEE Standard 1149.1-1990 Required Instructions, Optional INTEST, and P1149.1A CLAMP and HIGHZ
  - Parallel Signature Analysis at Inputs With Masking Option
  - Pseudo-Random Pattern Generation From Outputs
  - Sample Inputs/Toggle Outputs
  - Binary Count From Outputs
  - Device Identification
  - Even-Parity Opcodes
- Packaged in 64-Pin Plastic Shrink Quad Flat Pack (PM) and 68-Pin Ceramic Quad Flat Pack (HV)

SN54ABT18652 . . . HV PACKAGE  
(TOP VIEW)



NC – No internal connection

PRODUCT PREVIEW

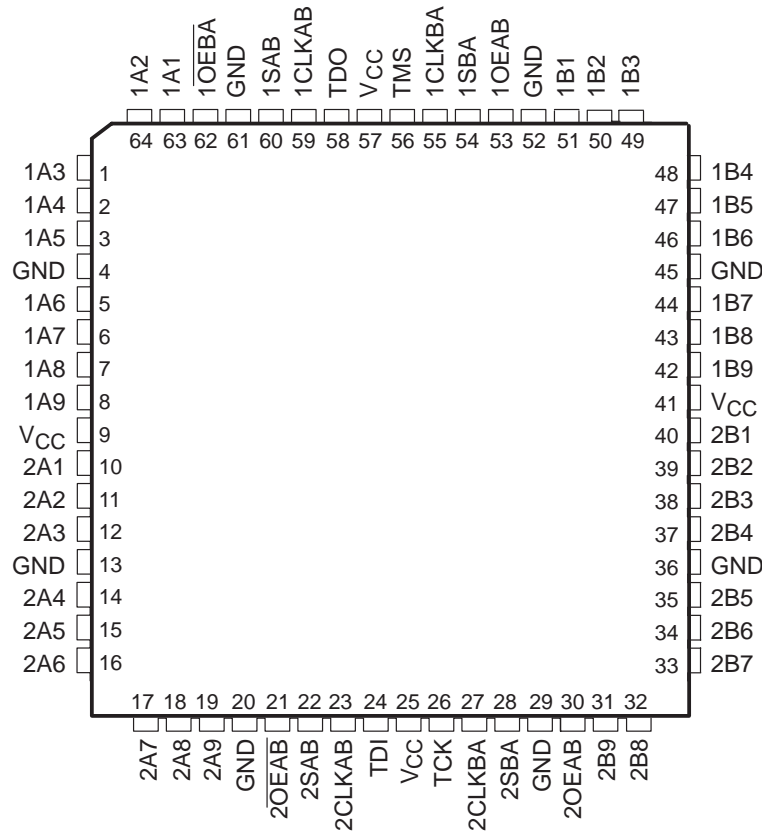
PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



# SN54ABT18652, SN74ABT18652 SCAN TEST DEVICES WITH 18-BIT BUS TRANSCEIVERS AND REGISTERS

SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

SN74ABT18652 . . . PM PACKAGE  
(TOP VIEW)



PRODUCT PREVIEW

## description

The SN54ABT18652 and SN74ABT18652 scan test devices with 18-bit bus transceivers and registers are members of the Texas Instruments SCOPE™ testability IC family. This family of devices supports IEEE Standard 1149.1-1990 boundary scan to facilitate testing of complex circuit board assemblies. Scan access to the test circuitry is accomplished via the 4-wire test access port (TAP) interface.

In the normal mode, these devices are 18-bit bus transceivers and registers that allow for multiplexed transmission of data directly from the input bus or from the internal registers. They can be used either as two 9-bit transceivers or one 18-bit transceiver. The test circuitry can be activated by the TAP to take snapshot samples of the data appearing at the device pins or to perform a self test on the boundary test cells. Activating the TAP in the normal mode does not affect the functional operation of the SCOPE™ bus transceivers and registers.

Data flow in each direction is controlled by clock (CLKAB and CLKBA), select (SAB and SBA), and output-enable (OEAB and OEBA) inputs. For A-to-B data flow, data on the A bus is clocked into the associated registers on the low-to-high transition of CLKAB. When SAB is low, real-time A data is selected for presentation to the B bus (transparent mode). When SAB is high, stored A data is selected for presentation to the B bus (registered mode). When OEAB is high, the B outputs are active. When OEAB is low, the B outputs are in the high-impedance state. Control for B-to-A data flow is similar to that for A-to-B data flow but uses CLKBA, SBA, and OEBA inputs. Since the OEBA input is active-low, the A outputs are active when OEBA is low and are in the high-impedance state when OEBA is high. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT18652.



**description (continued)**

In the test mode, the normal operation of the SCOPE™ bus transceivers and registers is inhibited, and the test circuitry is enabled to observe and control the I/O boundary of the device. When enabled, the test circuitry can perform boundary scan test operations according to the protocol described in IEEE Standard 1149.1-1990.

Four dedicated test pins are used to observe and control the operation of the test circuitry: test data input (TDI), test data output (TDO), test mode select (TMS), and test clock (TCK). Additionally, the test circuitry can perform other testing functions such as parallel signature analysis on data inputs and pseudo-random pattern generation from data outputs. All testing and scan operations are synchronized to the TAP interface.

Additional flexibility is provided in the test mode through the use of two boundary scan cells (BSCs) for each I/O pin. This allows independent test data to be captured and forced at either bus (A or B). A PSA/COUNT instruction is also included to ease the testing of memories and other circuits where a binary count addressing scheme is useful.

The SN54ABT18652 is characterized over the full military temperature range of –55°C to 125°C. The SN74ABT18652 is characterized for operation from –40°C to 85°C.

**FUNCTION TABLE**  
 (normal mode, each 9-bit section)

INPUTS						DATA I/O		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1 THRU A9	B1 THRU B9	
L	H	L	L	X	X	Input disabled	Input disabled	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	L	X	X	Input	Unspecified†	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	L	↑	X	X	Unspecified†	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	L	X	H	X	Input	Output	Stored A data to B bus
H	L	L	L	H	H	Output	Output	Stored A data to B bus and stored B data to A bus

† The data output functions can be enabled or disabled by a variety of level combinations at the OEAB or  $\overline{OEBA}$  inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition on the clock inputs.

‡ Select control = L: clocks can occur simultaneously.  
 Select control = H: clocks must be staggered in order to load both registers.

**PRODUCT PREVIEW**

PRODUCT PREVIEW

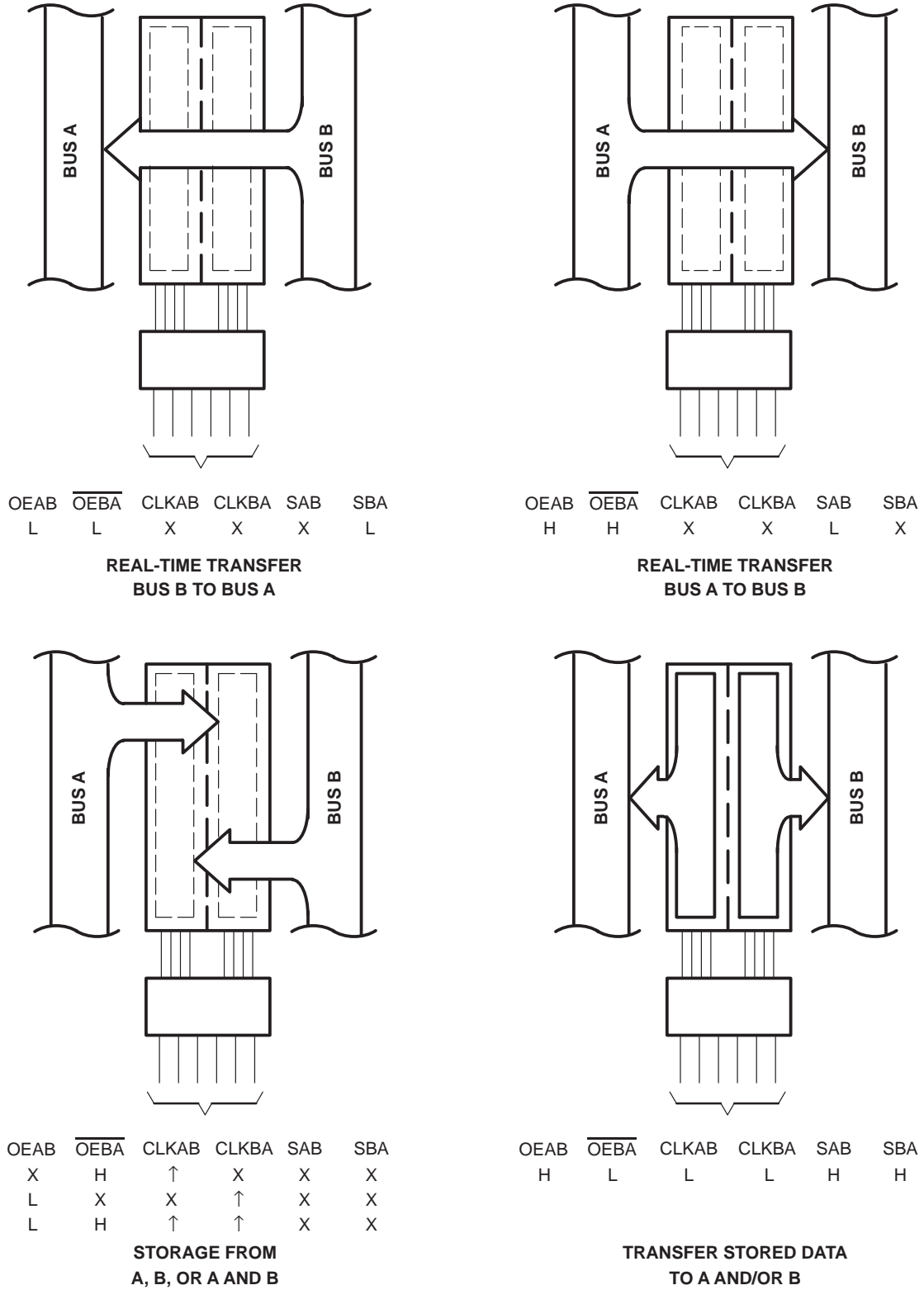
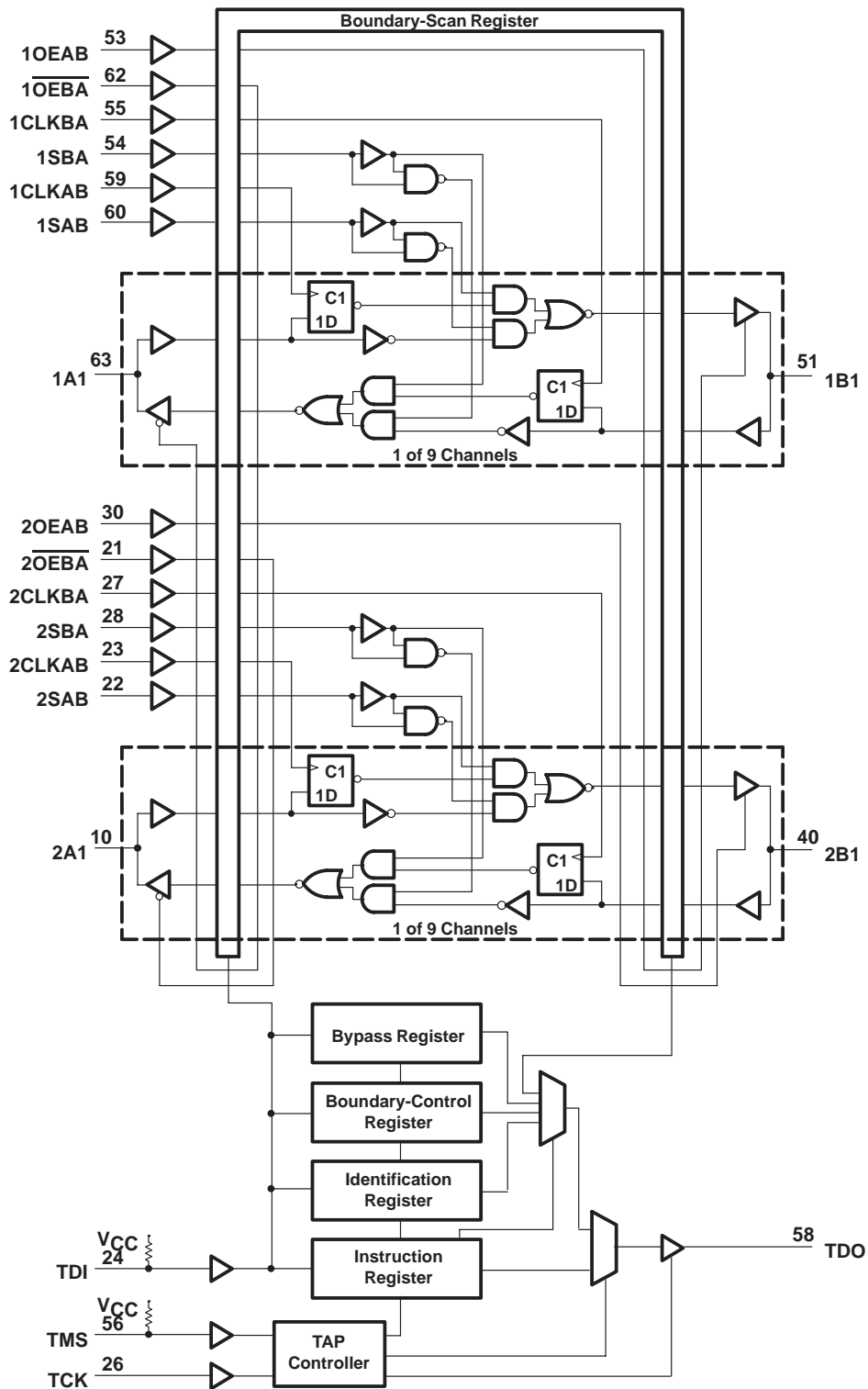


Figure 1. Bus-Management Functions

functional block diagram



Pin numbers shown are for the PM package.

PRODUCT PREVIEW

**SN54ABT18652, SN74ABT18652**  
**SCAN TEST DEVICES WITH**  
**18-BIT BUS TRANSCEIVERS AND REGISTERS**

SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage range, $V_I$ : except I/O ports (see Note 1) .....	–0.5 V to 7 V
I/O ports (see Note 1) .....	–0.5 V to 5.5 V
Voltage range applied to any output in the high state or power-off state, $V_O$ .....	–0.5 V to 5.5 V
Current into any output in the low state, $I_O$ : SN54ABT18652 .....	96 mA
SN74ABT18652 .....	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2) .....	885 mW
Storage temperature range .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. For the SN74ABT18652 (PM package), the power derating factor for ambient temperatures greater than 55°C is –10.5 mW/°C.

**recommended operating conditions (see Note 3)**

	SN54ABT18652		SN74ABT18652		UNIT
	MIN	MAX	MIN	MAX	
$V_{CC}$ Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$ High-level input voltage	2		2		V
$V_{IL}$ Low-level input voltage		0.8		0.8	V
$V_I$ Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$ High-level output current		–24		–32	mA
$I_{OL}$ Low-level output current		48		64	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		10		10	ns/V
$T_A$ Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

PRODUCT PREVIEW



SN54ABT18652, SN74ABT18652  
SCAN TEST DEVICES WITH  
18-BIT BUS TRANSCEIVERS AND REGISTERS  
SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Note 4)

PARAMETER	TEST CONDITIONS		T <sub>A</sub> = 25°C			SN54ABT18652		SN74ABT18652		UNIT	
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA		-1.2			-1.2		-1.2		V	
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -3 mA		2.5			2.5		2.5		V	
	V <sub>CC</sub> = 5 V, I <sub>OH</sub> = -3 mA		3			3		3			
	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2					
I <sub>OH</sub> = -32 mA		2*					2				
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA	0.55			0.55				V	
		I <sub>OL</sub> = 64 mA	0.55*					0.55			
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND	CLK, OEAB, OEBA, S, TCK	±1			±1		±1		μA	
		A or B ports	±100			±100		±100			
I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub>	TDI, TMS	10			10		10		μA	
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = GND	TDI, TMS	-160			-160		-160		μA	
I <sub>OZH</sub> ‡	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V		50			50		50		μA	
I <sub>OZL</sub> ‡	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.5 V		-50			-50		-50		μA	
I <sub>off</sub>	V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> ≤ 5.5 V		±100			±450		±100		μA	
I <sub>CEX</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high	50			50		50		μA	
I <sub>O</sub> §	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA	
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	A or B ports	Outputs high	4			4		4		mA
			Outputs low	80			80		80		
			Outputs disabled	4			4		4		
ΔI <sub>CC</sub> ¶	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND		1.5			1.5		1.5		mA	
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V	Control inputs	4							pF	
C <sub>io</sub>	V <sub>O</sub> = 2.5 V or 0.5 V	A or B ports	10							pF	
C <sub>o</sub>	V <sub>O</sub> = 2.5 V or 0.5 V	TDO	8							pF	

NOTE 4: Preliminary specifications based on SPICE analysis

\* On products compliant to MIL-STD-883, Class B, this parameter does not apply.

† All typical values are at V<sub>CC</sub> = 5 V.

‡ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

PRODUCT PREVIEW



**SN54ABT18652, SN74ABT18652**  
**SCAN TEST DEVICES WITH**  
**18-BIT BUS TRANSCEIVERS AND REGISTERS**

SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

**timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (normal mode) (see Note 4 and Figure 2)**

			SN54ABT18652		SN74ABT18652		UNIT
			MIN	MAX	MIN	MAX	
$f_{\text{clock}}$	Clock frequency	CLKAB or CLKBA	0	100	0	100	MHz
$t_w$	Pulse duration	CLKAB or CLKBA high or low			3		ns
$t_{\text{su}}$	Setup time	A before CLKAB $\uparrow$ or B before CLKBA $\uparrow$			5		ns
$t_h$	Hold time	A after CLKAB $\uparrow$ or B after CLKBA $\uparrow$			0		ns

**timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (test mode) (see Note 4 and Figure 2)**

			SN54ABT18652		SN74ABT18652		UNIT
			MIN	MAX	MIN	MAX	
$f_{\text{clock}}$	Clock frequency	TCK	0	50	0	50	MHz
$t_w$	Pulse duration	TCK high or low			5		ns
$t_{\text{su}}$	Setup time	A, B, CLK, OEAB, $\overline{\text{OEBA}}$ , or S before TCK $\uparrow$			5		ns
		TDI before TCK $\uparrow$			6		
		TMS before TCK $\uparrow$			6		
$t_h$	Hold time	A, B, CLK, OEAB, $\overline{\text{OEBA}}$ , or S after TCK $\uparrow$			0		ns
		TDI after TCK $\uparrow$			0		
		TMS after TCK $\uparrow$			0		
$t_d$	Delay time	Power up to TCK $\uparrow$			50		ns
$t_r$	Rise time	$V_{\text{CC}}$ power up			1		$\mu\text{s}$

NOTE 4: Preliminary specifications based on SPICE analysis

PRODUCT PREVIEW





SN54ABT18652, SN74ABT18652  
SCAN TEST DEVICES WITH  
18-BIT BUS TRANSCEIVERS AND REGISTERS  
SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (normal mode) (see Note 4 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT18652		SN74ABT18652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>	CLKAB or CLKBA		100	130		100		100		MHz
t <sub>PLH</sub>	A or B	B or A						1	6	ns
t <sub>PHL</sub>			1	6						
t <sub>PLH</sub>	CLKAB or CLKBA	B or A						2	6	ns
t <sub>PHL</sub>			2	6						
t <sub>PLH</sub>	SAB or SBA	B or A						2	8	ns
t <sub>PHL</sub>			2	8						
t <sub>PZH</sub>	OEAB or OEBA	B or A						2	7.5	ns
t <sub>PZL</sub>			2	7.5						
t <sub>PHZ</sub>	OEAB or OEBA	B or A						2	7.5	ns
t <sub>PLZ</sub>			2	7.5						

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (test mode) (see Note 4 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT18652		SN74ABT18652		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>	TCK		50	90		50		50		MHz
t <sub>PLH</sub>	TCK↓	A or B						3	12	ns
t <sub>PHL</sub>			3	12						
t <sub>PLH</sub>	TCK↓	TDO						2	7	ns
t <sub>PHL</sub>			2	7						
t <sub>PZH</sub>	TCK↓	A or B						3	14	ns
t <sub>PZL</sub>			3	14						
t <sub>PZH</sub>	TCK↓	TDO						2	8	ns
t <sub>PZL</sub>			2	8						
t <sub>PHZ</sub>	TCK↓	A or B						3	14	ns
t <sub>PLZ</sub>			3	14						
t <sub>PHZ</sub>	TCK↓	TDO						2	8	ns
t <sub>PLZ</sub>			2	8						

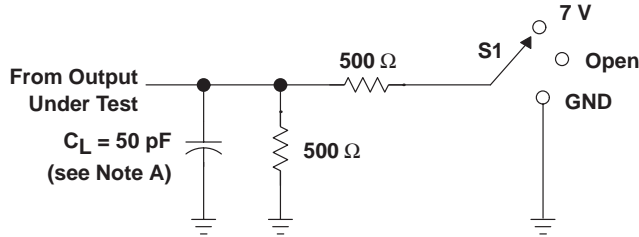
NOTE 4: Preliminary specifications based on SPICE analysis

PRODUCT PREVIEW

# SN54ABT18652, SN74ABT18652 SCAN TEST DEVICES WITH 18-BIT BUS TRANSCEIVERS AND REGISTERS

SCBS132A – AUGUST 1992 – REVISED OCTOBER 1992

## PARAMETER MEASUREMENT INFORMATION

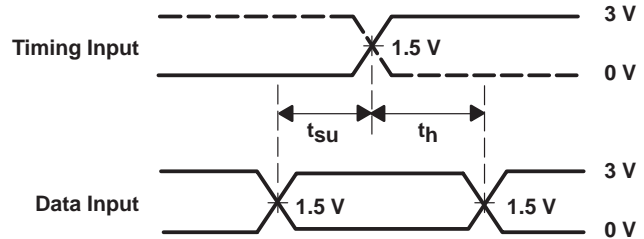


LOAD CIRCUIT FOR OUTPUTS

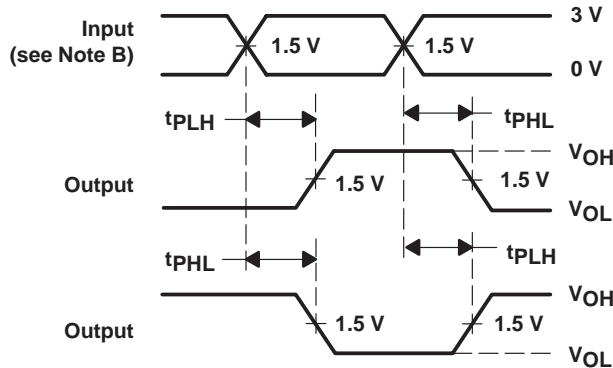
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



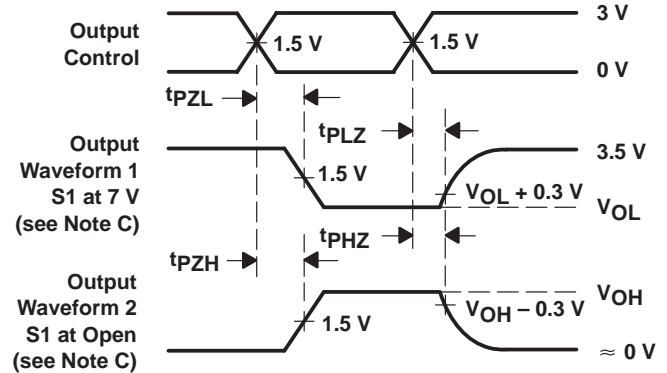
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NON-INVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.  
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PRODUCT PREVIEW

## IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.